

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Kah Wee Gan	04/25/2011
Yonggang Jin	04/25/2011
Yun Liu	04/25/2011
Yaohuang Huang	04/25/2011
RECEIVING PARTY DATA	
Name:	STMicroelectronics Pte Ltd.
Street Address:	28 Ang Mo Kio Industrial Park 2
City:	Singapore
State/Country:	SINGAPORE
Postal Code:	569508
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	13098083
CORRESPONDENCE DATA	
Fax Number:	(206)682-6031
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>	
Phone:	206-622-4900
Email:	laurah@seedip.com
Correspondent Name:	David C. Conlee
Address Line 1:	701 Fifth Avenue
Address Line 2:	Suite 5400
Address Line 4:	Seattle, WASHINGTON 98104
ATTORNEY DOCKET NUMBER:	851663.520C1
NAME OF SUBMITTER:	David C. Conlee
Total Attachments: 2 source=520C1_ASSIGN#page1.tif source=520C1_ASSIGN#page2.tif	

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ASSIGNMENT

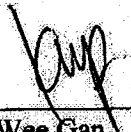
WHEREAS, we, Kah Wee Gan; Yonggang Jin; Yun Liu and Yaohuang Huang (hereinafter referred to as ASSIGNORS), having mailing addresses of No 7-1, Jalan Putera, Taman Putera Bakri, Muar, Johor Malaysia 84000; Blk 276 #10-134 Bangkit Road, Singapore; 629 Lorong 4/6 Toa Payoh, Singapore 319521; and Blk 725, #11-494, Woodlands Ave. 6, Singapore 730725, respectively, are the joint inventors of an invention entitled "THROUGH HOLE VIA FILLING USING ELECTROLESS PLATING," as described and claimed in the specification for which an application for United States letters patent was filed on _____ April 29, 2011, and assigned Application No. 13/098,083;

WHEREAS, STMicroelectronics Pte Ltd. (hereinafter referred to as ASSIGNEE), a corporation of the Country of Singapore having a place of business at 28 Ang Mo Kio Industrial Park 2, Singapore 569508, is desirous of acquiring the entire right, title and interest in and to the invention and in and to any letters patent that may be granted therefor in the United States and in any and all foreign countries;

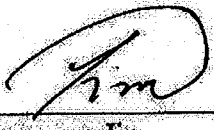
NOW, THEREFORE, in exchange for good and valuable consideration, the receipt of which is hereby acknowledged, ASSIGNORS hereby sell, assign and transfer unto said ASSIGNEE the entire right, title and interest in and to said invention, said application and any and all letters patent which may be granted for said invention in the United States of America and its territorial possessions including any extensions or adjustments in term thereof and in any and all foreign countries, and in any and all divisions, reissues and continuations thereof, including the right to file foreign applications directly in the name of ASSIGNEE and to claim priority rights deriving from said United States application to which said foreign applications are entitled by virtue of international convention, treaty or otherwise, said invention, application and all letters patent on said invention to be held and enjoyed by ASSIGNEE and its successors and assigns as fully and entirely as the same would have been held and enjoyed by ASSIGNORS had this assignment, transfer and sale not been made. ASSIGNORS hereby authorize and request the Commissioner of Patents and Trademarks to issue all letters patent on said invention to ASSIGNEE. ASSIGNORS agree to execute all instruments and documents required for the making and prosecution of applications for United States and foreign letters patent on said invention, for litigation regarding letters patent, or for the purpose of protecting title to said invention or letters patent therefor.

Assignee's counsel is authorized to insert the official filing date and application number information when it becomes available.


25/4/11
Date


Kah Wee Gan


25/4/11
Date


Yonggang Jin

25/4/2011
Date


Yun Liu

25/4/2011
Date


Yaohuang Huang

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